



Cookson Electronics ASSEMBLY MATERIALS

Alpha Metals Korea

1Ra310, Sihwa Industrial Complex, 1247-9, Jungwang-Dong, Siheong-Si, Gyeonggi-Do, Korea. Tel : 82)31-433-1460-1 Fax : 82)31-433-1478

BGA UP-78

BGA/CSP No Clean Flux

No Clean paste flux BGA UP78 pin test

. Reflow

ATE

. BGA/CSP Flux

IC package bumping

repair

solder sphere

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(Spiral/Malcom)

Light amber/ 1.0g/cm<sup>3</sup>

180 POISE(30rpm)

>6g/mm<sup>2</sup>

Stencil life

~8 hours(40~60%RH/20~25 )

Tack free

Corrosivity

Passes Copper Mirror

Halide Content

Passes Silver Chromate Paper Test

(REL -1 IPC J-STD-004)

J-STD-004 SIR(pass>10<sup>8</sup>)

>2x 10<sup>9</sup>ohms,7days,uncleaned,comb down

J-STD-004 SIR(pass>10<sup>8</sup>)

>3x 10<sup>9</sup>ohms,7days,uncleaned,comb up

BELLCORE SIR(pass>10<sup>11</sup>)

>1x 10<sup>12</sup>ohms,4days,uncleaned,comb down

BELLCORE SIR(pass>10<sup>11</sup>)

>3x 10<sup>12</sup>ohms,4days,uncleaned,comb up

Electromigration(500hours)

4.6x 10<sup>10</sup>ohms,initial

(BELLCORE)

1.8x 10<sup>10</sup>ohms, 500hours(passes)

REFLOW

Reflow

dry air

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ramp rate : 60~120 /min

110~130 (

110~130

1~2

dwel time 가 )

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assembly

CSP/BGA

furnace load

equilibrium

dwel

: ramp 60~120 --> 210~225

alloy liquidus

45~90sec Max.

(183 for 63Sn/37Pb or 179 for 62Sn/36Pb/2Ag)

Cooling rate : 90~120 /min -->



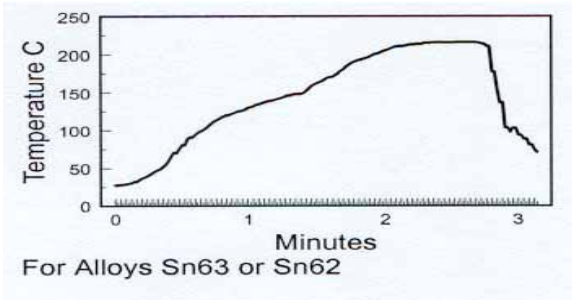
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Stencil print, pin transfer, dispensing. PBGA  
Flux

Chip Scale package substrate

saponifier

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BIOACT EC7-R™

BIOACT EC7-R™

10% Alpha 2110

stencil

pin

BGA78 10 30cc syringe, 6" cartridges, jar

. 27

12

flux

BGA78

reflow

가

가

MSDS

BIOACT, EC-7R, EC-ULTRA, SC-10

Petroferm Inc